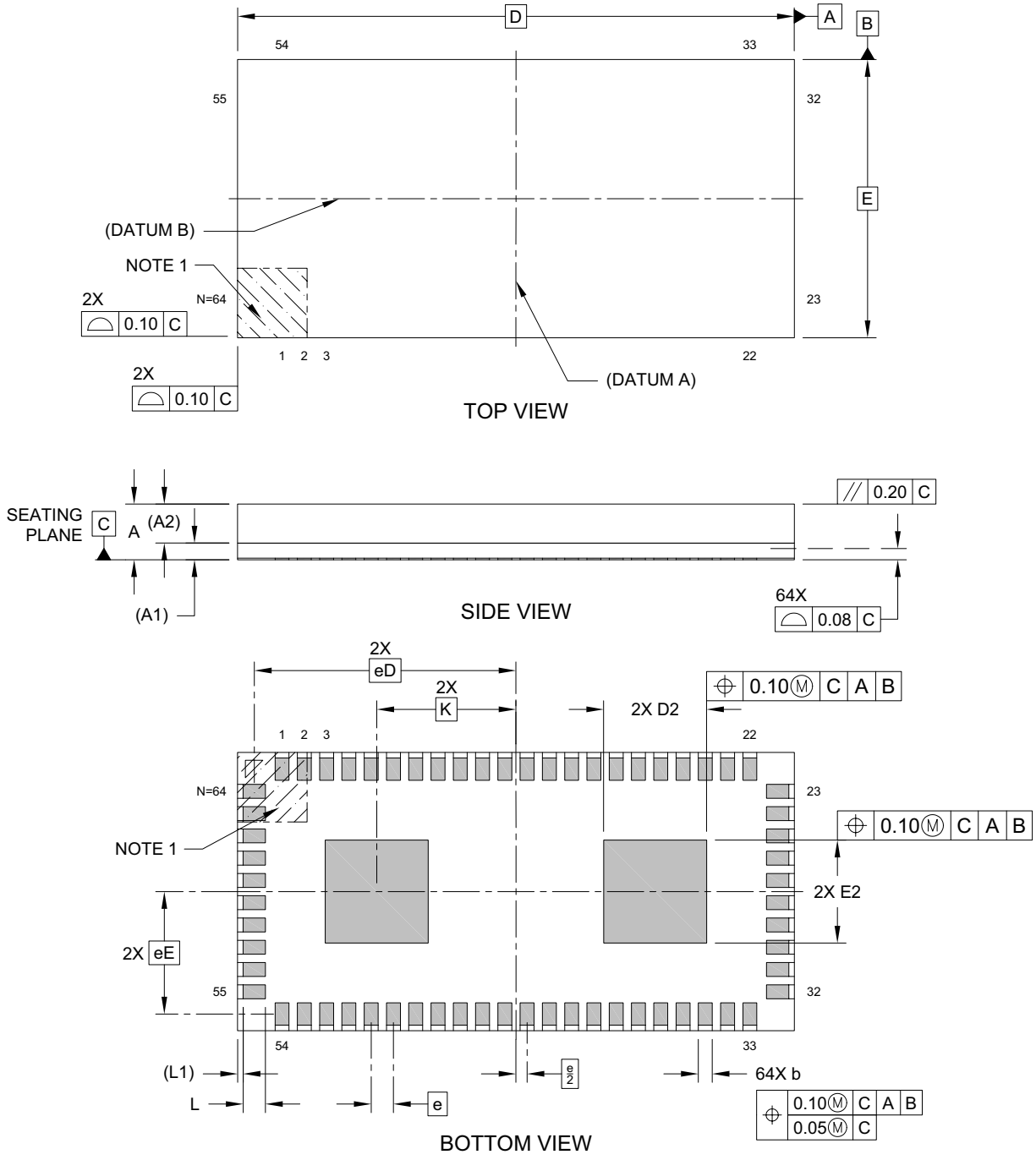
64-Lead Very Thin Fine Pitch Land Grid Array (JVC) - 10x5x1.0 mm Body [VFLGA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



64-Lead Very Thin Fine Pitch Land Grid Array (JVC) - 10x5x1.0 mm Body [VFLGA]

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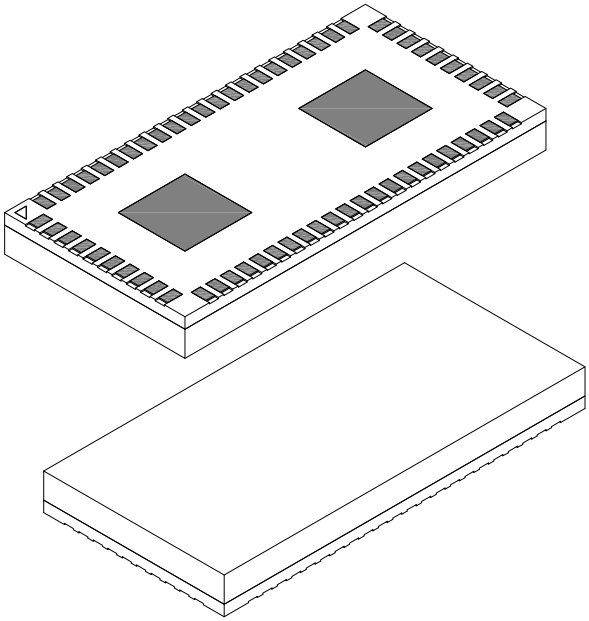

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Terminals	N		64	
Pitch	e		0.40 BSC	
Package Center to Terminal Center (X2)	eD		4.70 BSC	
Package Center to Terminal Center (X2)	eE		2.20 BSC	
Overall Height	A	–	–	1.00
Substrate Thickness	A1		0.19 REF	
Mold Cap Thickness	A2		0.70 REF	
Overall Length	D		10.00 BSC	
Exposed Pad Length (X2)	D2	1.80	1.85	1.90
Package Center to Exposed Pad Center (X2)	K		2.50 BSC	
Overall Width	E		5.00 BSC	
Exposed Pad Width (X2)	E2	1.80	1.85	1.90
Terminal Width	b	0.20	0.25	0.30
Terminal Length	L	0.35	0.40	0.45
Terminal Pullback	L1		0.10 REF	

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Dimensioning and tolerancing per ASME Y14.5M
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
   REF: Reference Dimension, usually without tolerance, for information purposes only.

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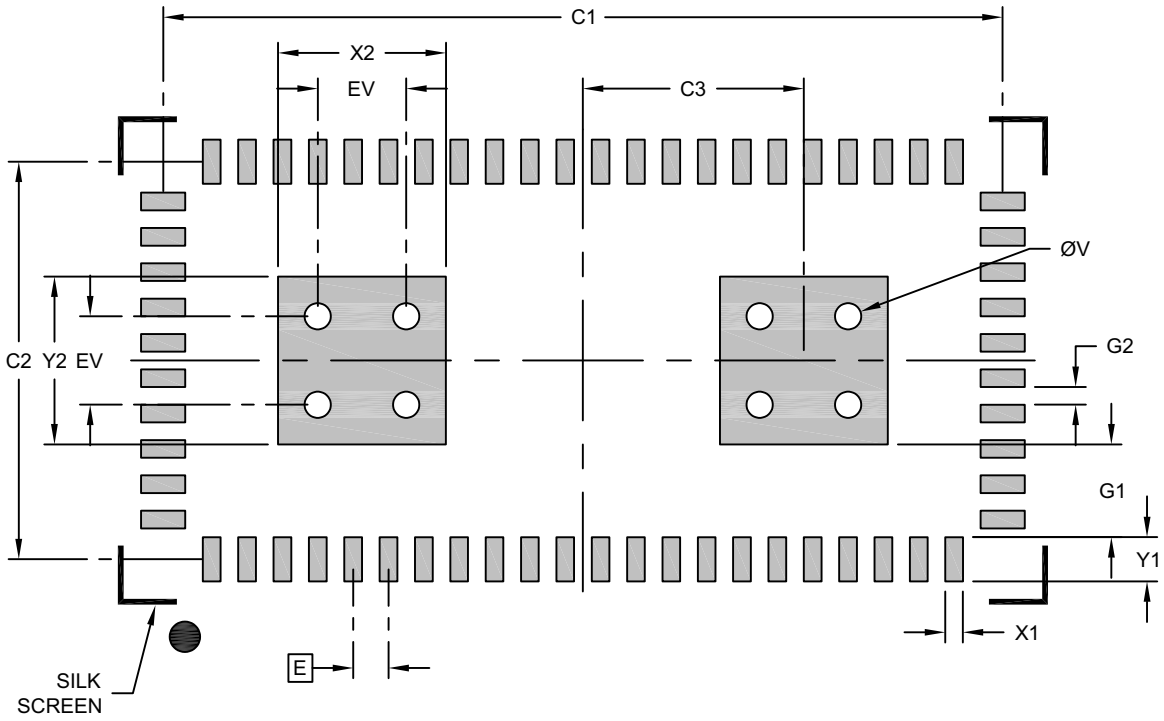

RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.40 BSC	
Center Pad Width	X2			1.90
Center Pad Length	Y2			1.90
Contact Pad Spacing	C1		9.50	
Contact Pad Spacing	C2		4.50	
Package Center to Pad Center (X2)	C3		2.50	
Contact Pad Width (X64)	X1			0.20
Contact Pad Length (X64)	Y1			0.50
Contact Pad to Center Pad (X64)	G1	1.05		
Contact Pad to Contact Pad (X60)	G2	0.20		
Thermal Via Diameter	V		0.30	
Thermal Via Pitch	EV		1.00	

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

2. For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process

Microchip Technology Drawing C04-27352 Rev A